Benvenuto in O-Leading

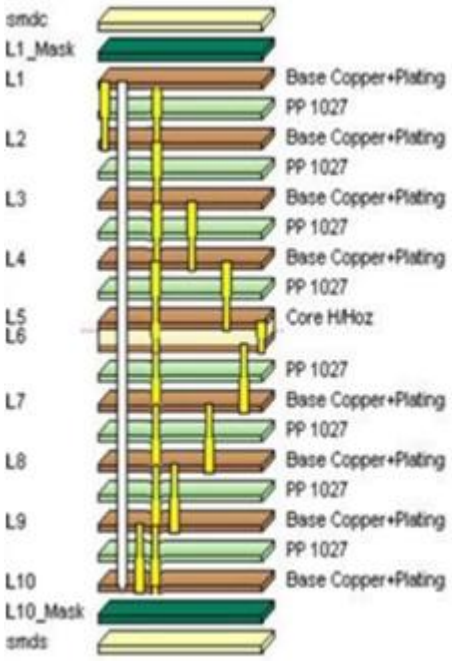
O-Leading si impegna per essere il partner della soluzione one stop nella catena di fornitura EMS, tra cui progettazione PCB, fabbricazione PCB e assemblaggio PCB (PCBA). Forniamo alcune delle tecnologie PCB più avanzate, tra cui PCB HDI, PCB multistrato, PCB rigidi-flessibili Siamo in grado di supportare dal prototipo a rotazione rapida alla produzione media e di massa. fornitore di circuiti stampati

In generale, i nostri clienti globali sono molto colpiti dai nostri servizi: risposta rapida, prezzo competitivo e impegno di qualità. Fornire un servizio tecnico più prezioso e una soluzione globale è il modo in cui O-leader in avanti.

Guardando al futuro, O-Leading si concentrerà sull'innovazione e sullo sviluppo della tecnologia di produzione elettronica come sempre e farà sforzi costanti sul servizio one-stop PCB e PCBA per fornire servizi di prima classe e creare più valore per i nostri clienti.

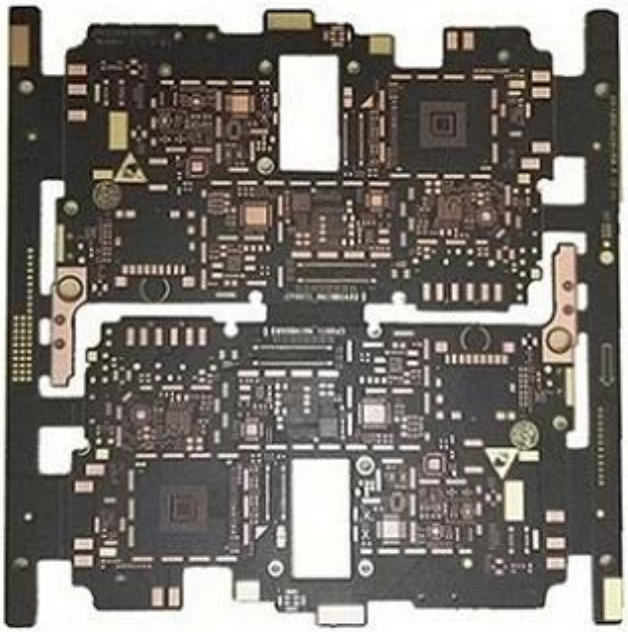
Siamo produttori di PCB professionali con dieci anni di esperienza. Gamma di prodotti: PCB singolo, doppio lato, multistrato, PCB flessibile e MCPCB.
Siamo in grado di fornire un servizio di prototipazione veloce: S / S in 24 ore, 4-8 giocatori in 48-96 ore lavorative di produzione. Circuito stampato oem per telefoni cellulari con alimentatore.
Fori lastre di rame minimo 0,025 avg, 0,020 min. I fori non possono essere tappati.
Confezione con pellicola a bolle trasparente incolore, 25 pezzi / sacchetto, mettere l'essiccante nel fianco, mettere la scheda dell'indicatore di umidità sul lato superiore.
produttore di PCB multistrato in Cina

Struttura a strati



O-LEADING

To Be Reliable, To Be Valuable



www.o-leading.com

O-LEADING

To Be Reliable, To Be Valuable

www.o-leading.com

Grossisti pcb di alta qualità

La nostra squadra


O-LEADING

Factory PCB

Automatic vacuum press machine

Drilling Machine

Pattern Plating Machine

Scrubbing Machine

Developing Machine

Routing Machine

High-speed flying probe machine

E-test Machine

Factory SMT

certificazioni

CICC CERTIFICATION
INSPECTION CERTIFICATION

CICC CERTIFICATION
嘉泰认证

QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No: 18118Q10347R0S

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No：61691591-000-07-18-7

Registration Add: FLAT/RM 1205 12/F TAI SANG BANK BUILDING 130-132 DES VOEUS ROAD CENTRAL HK

Business Add: 1313, Floor 13, Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System**

Which fulfils the requirements of the following standards

GB/T19001-2016 idt ISO9001:2015

Scope of certification

Sales of printed circuit boards

Initial Issuance period: February 27, 2018

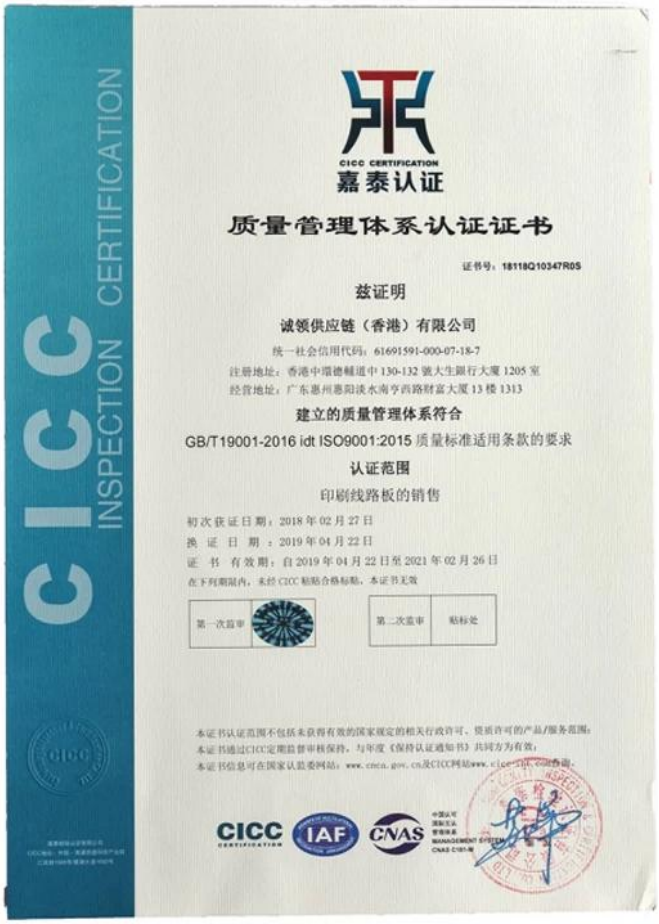
Renewal date: April 22, 2019

This certificate is valid during: April 22, 2019 ~ February 26, 2021

This certificate is invalid without CICC qualified label in the following period

First supervision and audit		Second supervision and audit	Qualified mark

CICC IAF CNAS



CICC CERTIFICATION
INSPECTION CERTIFICATION

CICC CERTIFICATION
嘉泰认证

质量管理体系认证证书

证书号：18118Q10347R0S

兹证明

诚领供应链（香港）有限公司

统一社会信用代码：61691591-000-07-18-7

注册地址：香港中環德輔道中 130-132 號大生銀行大廈 1205 室

经营地址：广东惠州惠阳淡水南亨西路财富大厦 13 楼 1313

建立的质量管理体系符合

GB/T19001-2016 idt ISO9001:2015 质量标准适用条款的要求

认证范围

印刷线路板的销售

初次获证日期：2018 年 02 月 27 日

换 证 日 期 ：2019 年 04 月 22 日

证 书 有 效 期：自 2019 年 04 月 22 日至 2021 年 02 月 26 日

在下列期限内，未经 CICC 贴贴合格标贴，本证书无效

第一次监审		第二次监审	贴标处

本证书认证范围不包括未获得有效的国家规定的相关行政许可、资质许可的产品/服务范围；

本证书通过CICC定期监督审核保持，与年度《保持认证通知书》共同方为有效；

本证书信息可在国家认监委网站：www.cnca.gov.cn及CICC网站www.cicc-cic.com查询。

CICC IAF CNAS

O-LEADING SUPPLY CHAIN (HK) CO.,LIMITED

1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. :	RP19-005089 - SZ
Date of Sample Received :	22 Mar 2019
Testing Period :	22 Mar 2019 - 30 Mar 2019
Test Requested :	Selected test(s) as requested by client.
Test Method :	Please refer to next page(s).
Test Results :	Please refer to next page(s).
Conclusion :	Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory

Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green"PCB"

Remarks :

(1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit
(3) ND = Not Detected (< MDL)
(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

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Attention: To check the authenticity of testing /inspection report & certificate, please contact us at telephone: (86-755) 8307 1443, or email: CN.Doccheck@sgs.com
SGS-CSTC Standards Technical Services Co., Ltd.
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中国 · 深圳 · 龙岗区坂田吉华路430号江厦工业园4栋SGS大楼 邮编: 518129 t (86-755) 25328888 f (86-755) 83106190 e sgs.china@sgs.com
Member of the SGS Group (SGS SA)

UL Product iQ™

ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD
ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

E490354

Type	Cond Width Min mm(in)	Min Edge mm(in)	Cond Thk mic(mil)	SS/ DS/ DSO	Max Area Diam mm(in)	Solder Limits C	sec	Max Oper Temp C	Flame Class	Meets UL796 DSR	CTI
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

Imballaggio e consegna

Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Capacità di processo

Funzionalità di produzione di PCB

Conteggio strati: 1 strato-32 strati
Spessore rame finito □ 1 / 3oz-12oz
Larghezza min linea / spaziatura interna □ 3.0mil / 3.0mil
Larghezza min linea / spaziatura esterna: 4.0mil / 4.0mil
Rapporto di aspetto massimo: 10: 1
Spessore della scheda □ 0,2 mm-5,0 mm
Dimensione massima del pannello (pollici): 635 * 1500mm
Dimensione minima del foro: 4mil
Tolleranza del foro Plated: +/- 3mil
Blind / Buried Vias (tipi All): SÌ
Via Fill (conduttivo, non conduttivo): SÌ
Materiale base: FR-4, FR-4hg Tg. Materiale privo di alogeni, Rogers, Base in alluminio,poliimmide, Rame pesante
Finiture superficiali: HASL, OSP, ENIG, HAL-LF, argento mmmm,Immersion Tin, dita d'oro, inchiostro al carbonio

Capacità di produzione SMT

Materiale PCB: FR-4, CEM-1, CEM-3, scheda a base di alluminio
Dimensione massima PCB: 510x460mm
Dimensioni min PCB: x 50x50mm
Spessore PCB □ 0,5 mm-4,5 mm
Spessore della scheda □ 0,5-4mm
Dimensioni min componenti: 0201
Componente di dimensioni del chip standard: 0603 e superiori
Altezza massima componente □ 15mm
Passo minimo di piombo: 0,3 mm
Passo palla BGA min: 0.4mm
Precisione di posizionamento: +/- 0,03 mm